

## GTS217E

**N-CHANNEL ENHANCEMENT MODE POWER MOSFET**

BV <sub>DSS</sub>	20V
R <sub>DS(ON)</sub>	22mΩ
I <sub>D</sub>	7A

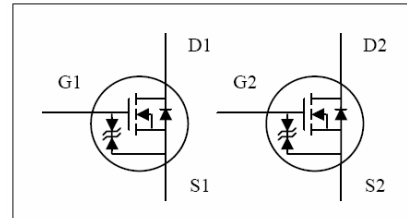
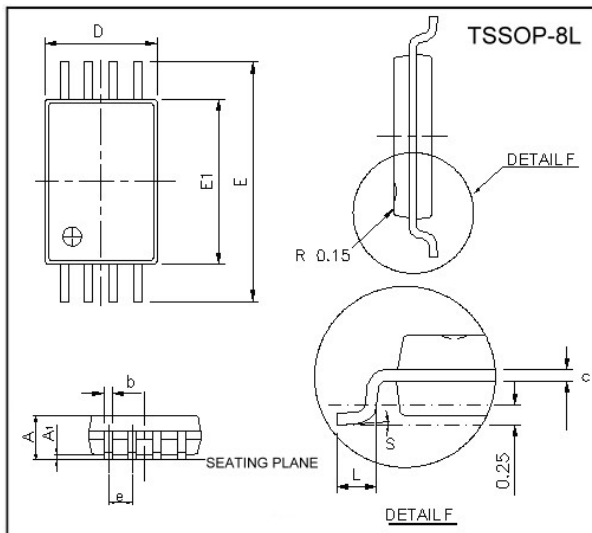
### Description

The GTS217E provides the designer with the best combination of fast switching, ruggedized device design, ultra low on-resistance and cost-effectiveness.

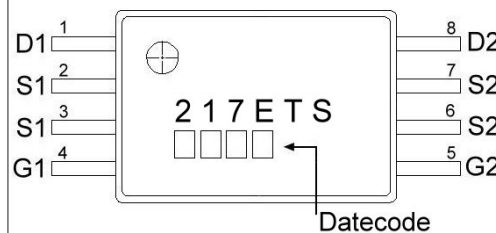
### Features

- \*Low on-resistance
- \*Capable of 2.5V gate drive
- \*Optimal DC/DC battery application

### Package Dimensions



### Marking:



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	-	1.20	E	6.20	6.60
A1	0.05	0.15	E1	4.30	4.50
b	0.19	0.30	e	0.65 BSC	
c	0.09	0.20	L	0.45	0.75
D	2.90	3.10	S	0°	8°

### Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Continuous Drain Current <sup>3</sup>	I <sub>D</sub> @TA=25°C	7	A
Continuous Drain Current <sup>3</sup>	I <sub>D</sub> @TA=70°C	5.7	A
Pulsed Drain Current <sup>1</sup>	I <sub>DM</sub>	30	A
Total Power Dissipation	P <sub>D</sub> @TA=25°C	1.5	W
Linear Derating Factor		0.012	W/°C
Operating Junction and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55 ~ +150	°C

### Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-ambient <sup>3</sup> Max.	R <sub>thj-a</sub>	83	°C/W

## Electrical Characteristics (T<sub>j</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	-	-	V	V <sub>GS</sub> =0, I <sub>D</sub> =250uA
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.5	-	1.0	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA
Forward Transconductance	g <sub>fs</sub>	-	24	-	S	V <sub>DS</sub> =5V, I <sub>D</sub> =7A
Gate-Source Leakage Current	I <sub>GSS</sub>	-	-	±10	uA	V <sub>GS</sub> = ±10V
Drain-Source Leakage Current(T <sub>j</sub> =25°C)	I <sub>DSS</sub>	-	-	1	uA	V <sub>DS</sub> =16V, V <sub>GS</sub> =0
Drain-Source Leakage Current(T <sub>j</sub> =55°C)		-	-	5	uA	V <sub>DS</sub> =16V, V <sub>GS</sub> =0
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	-	-	22	mΩ	V <sub>GS</sub> =4.5V, I <sub>D</sub> =6.6A
		-	-	30		V <sub>GS</sub> =2.5V, I <sub>D</sub> =5.5A
Total Gate Charge <sup>2</sup>	Q <sub>g</sub>	-	9.3	-	nC	I <sub>D</sub> =7A V <sub>DS</sub> =10V V <sub>GS</sub> =4.5V
Gate-Source Charge	Q <sub>gs</sub>	-	0.6	-		
Gate-Drain ("Miller") Change	Q <sub>gd</sub>	-	3.6	-		
Turn-on Delay Time <sup>2</sup>	T <sub>d(on)</sub>	-	820	-	ns	V <sub>DS</sub> =10V I <sub>D</sub> =1A V <sub>GS</sub> =4.5V R <sub>G</sub> =6Ω R <sub>L</sub> =10Ω
Rise Time	T <sub>r</sub>	-	934	-		
Turn-off Delay Time	T <sub>d(off)</sub>	-	860	-		
Fall Time	T <sub>f</sub>	-	510	-		
Input Capacitance	C <sub>iSS</sub>	-	231	-	pF	V <sub>GS</sub> =0V V <sub>DS</sub> =10V f=1.0MHz
Output Capacitance	C <sub>oss</sub>	-	164	-		
Reverse Transfer Capacitance	C <sub>rSS</sub>	-	137	-		

## Source-Drain Diode

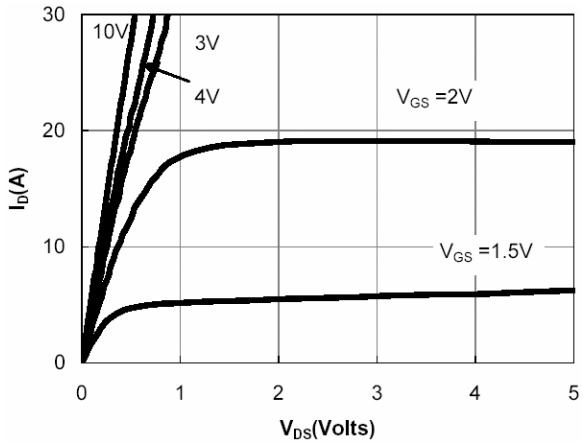
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage <sup>2</sup>	V <sub>SD</sub>	-	-	1.0	V	I <sub>S</sub> =1.0A, V <sub>GS</sub> =0V
Reverse Recovery Time <sup>2</sup>	T <sub>rr</sub>	-	15.2	-	ns	I <sub>S</sub> =7A, V <sub>GS</sub> =0V di/dt=100A/μs
Reverse Recovery Charge	Q <sub>rr</sub>	-	6.3	-	nC	
Continuous Source Current (Body Diode)	I <sub>S</sub>	-	-	2.5	A	V <sub>D</sub> =V <sub>G</sub> =0V, V <sub>S</sub> =1.0V

Notes: 1. Pulse width limited by Max. junction temperature.

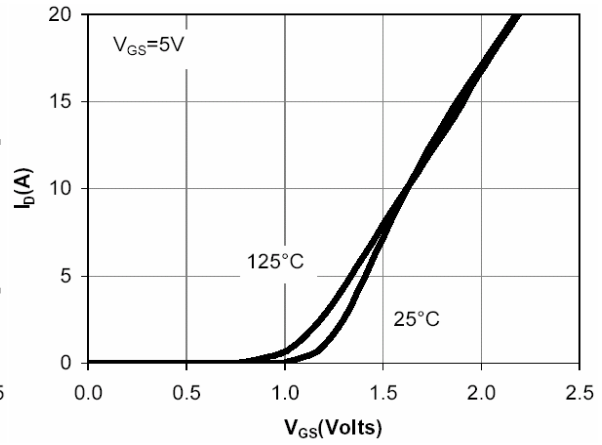
2. Pulse width ≤ 300us, duty cycle ≤ 2%.

3. Surface mounted on FR4 board, t ≤ 10sec.

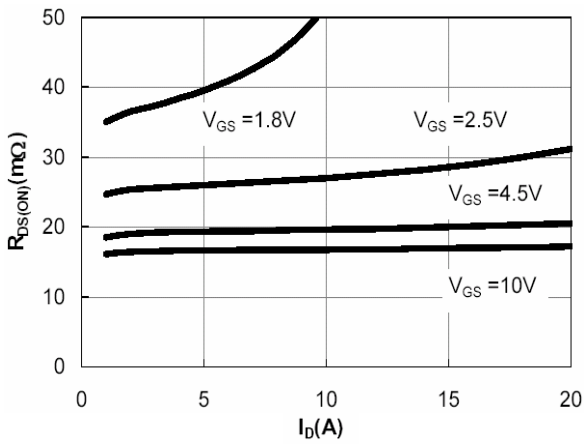
**Characteristics Curve**



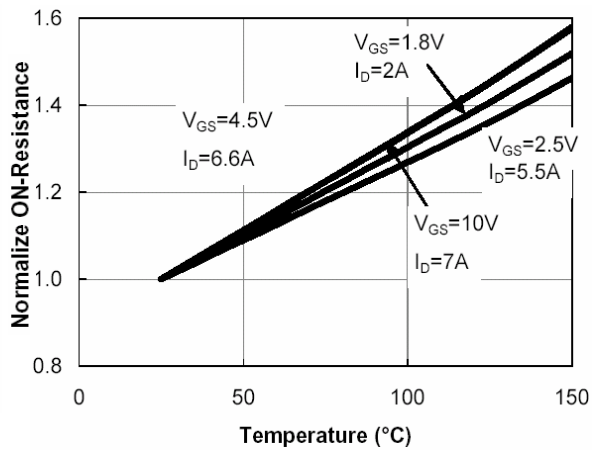
**Fig 1. Typical Output Characteristics**



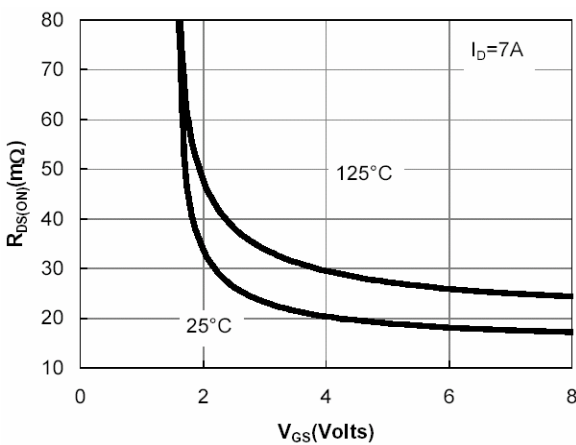
**Fig 2. Transfer Characteristics**



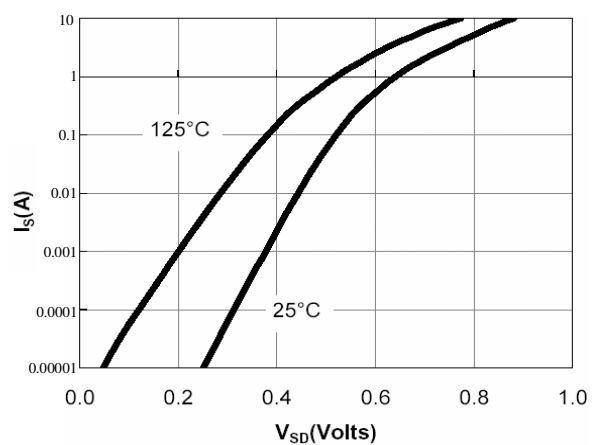
**Fig 3. On-Resistance v.s. Drain Current and Gate Voltage**



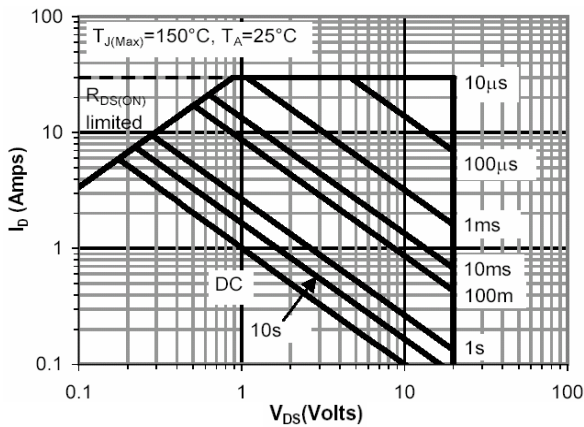
**Fig 4. On-Resistance v.s. Junction Temperature**



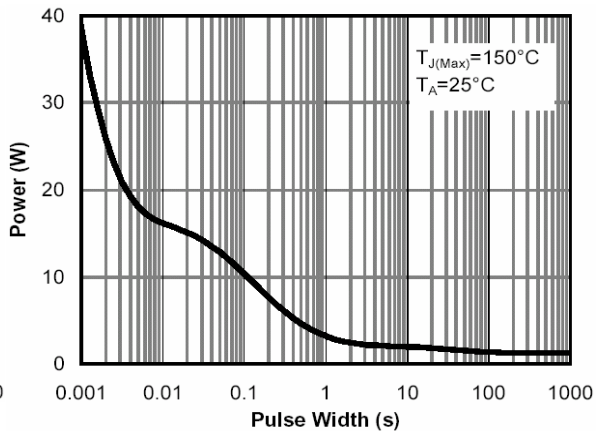
**Fig 5. On-Resistance v.s. Gate-Source Voltage**



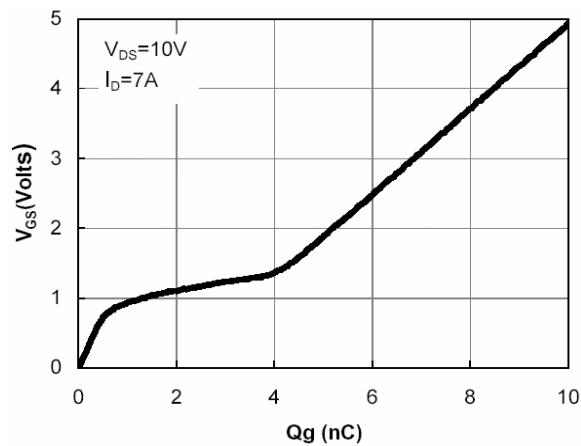
**Fig 6. Body Diode Characteristics**



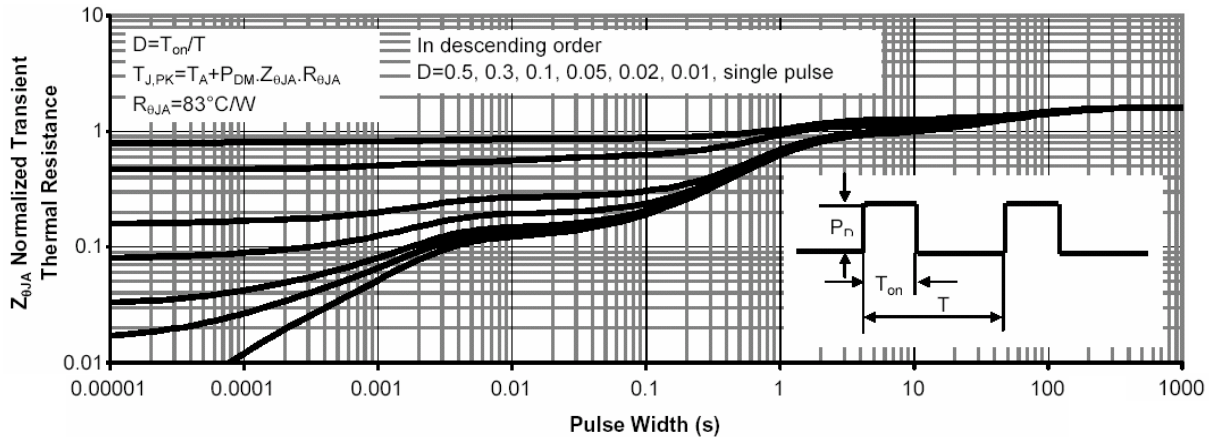
**Fig 7. Maximum Safe Operating Area**



**Fig 8. Single Pulse Power Rating Junction-to-Ambient**



**Fig 9. Gate Charge Characteristics**



**Fig 10. Normalized Maximum Transient Thermal Impedance**

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